

QUALI-FILL LIBRA® "A" Series

On-Line Chemical Management Systems

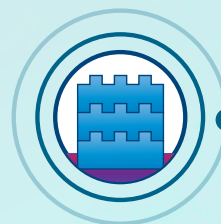
As production technologies continue to advance, IC Substrate and Printed Circuit Board (PCB) manufacturers are facing tighter plating specifications and ramped up demand. ECI's LIBRA "A" series Chemical Management Systems are designed to address these challenges in cutting edge, high volume manufacturing applications. Using this online system, producers of IC Substrates and PCBs can maintain optimal plating conditions, reducing the potential for voids and operator error, while significantly improving cost-of-ownership (CoO), and reliability.

Qualified for High Volume Manufacturing

LIBRA "A" series systems offer turnkey solutions for monitoring and control of:

- Desmear
- E-Less and Electrolytic Copper Deposition
- Sn or Sn alloy deposition for bumps or caps
- Ni-Pd-Au for UBM or final finishes

Smallest and most flexible modular design
Supporting multiple chemistries and tanks



Analyzer Health Monitor (AHM)
Maximum reliability and up-time



Automatic Standard Generator (ASG)*
No need to buy standard



Intelligent Dosing
Complete solution of monitoring and replenishment



We Keep Your Chemistry Right.™



QUALI-FILL LIBRA A Series

Precise, Reliable Monitoring and Control

Features

- Supports all known chemistries
- Automatic validation and calibration
- Comprehensive analysis of all components
- Automatic standard generation (ASG), validation and calibration*
- Analyzer Health Monitor (AHM) for predictive maintenance*
- Bath Health Monitor for yield improvement*
- Analytical techniques combined to achieve best performance & CoO
- S2/S8, CE Compliant

*-optional

Wide Range of Analytical Techniques

NIR Spectroscopy • UV-Vis Spectroscopy •
Cyclic Voltammetric Stripping • Potentiometric Titration •
Direct Monitoring with Highly Selective Sensors (Dissolved Oxygen,
pH, ISE, Surface Tension, Specific Gravity) •
Conductometric Titration • E-Chem Impedance •
OCP (Open Circuit Potentiometry) • HPLC • ICP • And Others!

Additional Processes

- Pd Activation
- E-less Ni
- Immersion Au
- Au Plating
- And more!

Meeting the Challenges of Today's PCB, IC Substrate, and Panel Level Packaging Applications

Backed by ECI Global Support

Don't hesitate to contact us for more details! Call or visit us online:
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